



Test methods for SEE evaluations of ADCs and DACs



## ESA-CNES Radiation Final Presentation Days on Space Environments and Radiation Effects on EEE components

ESTEC contract- No4000105495/12/NL/SFe

Main objective:

- Evaluate 3 ADCs and 1DAC as candidates for space applications
- Compare different test methods for SEE testing

# Parts Selection and criteria

- **Key drivers for converter selection:**
  - ADC128S102 and RHF1401 required in the study
  - 16 bits ADC or higher resolution
  - Space quality level availability
  
- **Parts selection has been performed according to the following criteria :**
  - Selection of different A/D converter architectures.

| reference  | Manufacturer       | type | Resolution | Sampling frequency | Comment                     | Architecture                                 |
|------------|--------------------|------|------------|--------------------|-----------------------------|--|
| AD976A     | Analog Devices     | A/D  | 16-bit     | 200kSPS            | BICMOS                      | Successive approximation, switched capacitor |
| ADC128S102 | Texas Instruments  | A/D  | 12-bit     | 50kSPS to 1MSPS    | 8 Channel                   | Successive approximation, switched capacitor |
| RHF1401    | STMicroelectronics | A/D  | 14-bit     | 20MSPS             | Rad-hard                    | Pipelined                                    |
| ADS1278    | Texas Instruments  | A/D  | 24-bit     | Up to 144kSPS      | Octal simultaneous sampling | Delta Sigma                                  |
| DAC5675A   | Texas Instruments  | D/A  | 14-bit     | 400MSPS            | Class V                     | current-source-array                         |

# SEE Test methods

- ✓ **Beat Frequency**
- ✓ **4 Points (4P)**
- ✓ **“hirex”**

(1) : Enhancing Observability of Signal Composition and Error Signatures during SEE Analog to Digital Testing’ – M. Berg et Al, IEEE Transactions on Nuclear Science, Volume 57, Issue: 4

# ADC: Beat frequency

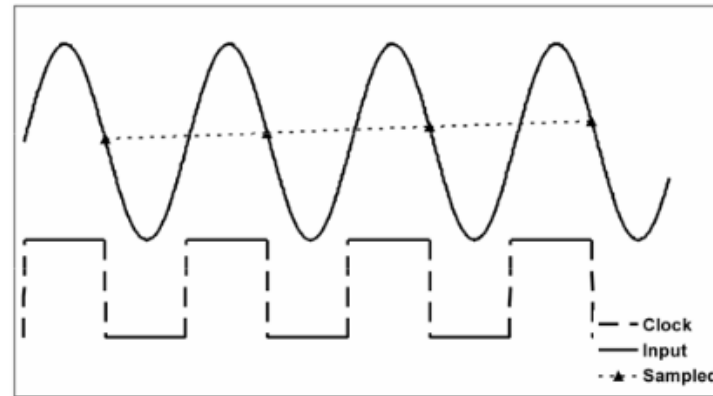
- With the input frequency  $f_{in}$  set very close to the sampling frequency  $f_s$ , the output code of the ADC is a slow moving digital sine wave, changing at a rate of 1 LSB per clock cycle.

$$f_{in} = f_s / (2^N * \pi) \text{ with } N = \text{A/D resolution}$$

Trig condition:

$$|\text{output at } \text{clk}-1 - \text{output at } \text{clk}| > \text{EB}$$

EB= given Error Bound



Event record:

If event trig → 4096 points are recorded including pretrig points

DUT sampling frequency being fixed, the selected frequency of the sinewave input is such that only 4 points of the sinewave input are converted continuously.

$$f_{in} = f_s / 4$$

Trig condition:

$$|\text{output at clk-4} - \text{output at clk}| > EB$$

Differs from 4P test method presented in (1) where each of the 4 points have its own EB

Pro:

- Same EB for any point

- No need of specific algorithm to recover from an upset in clocking system

- No need to record the DRY DUT signal

Con:

- Use of possibly larger margin in EB

Event record:

If event trig → 4096 points are recorded including pretrig points

(1) : Enhancing Observability of Signal Composition and Error Signatures during SEE Analog to Digital Testing' – M. Berg et Al, IEEE Transactions on Nuclear Science, Volume 57, Issue: 4

# ADC: “hirex” test method

DUT sampling frequency being fixed, input frequency  $f_{in}$  is set to a much lower value than  $f_s$  with  $f_s$  a multiple of  $f_{in}$ , leading to a significant number of points converted by sinewave input period (typically 100 to 2000 points)

$$f_{in} = f_s / m \text{ with } m \text{ integer}$$

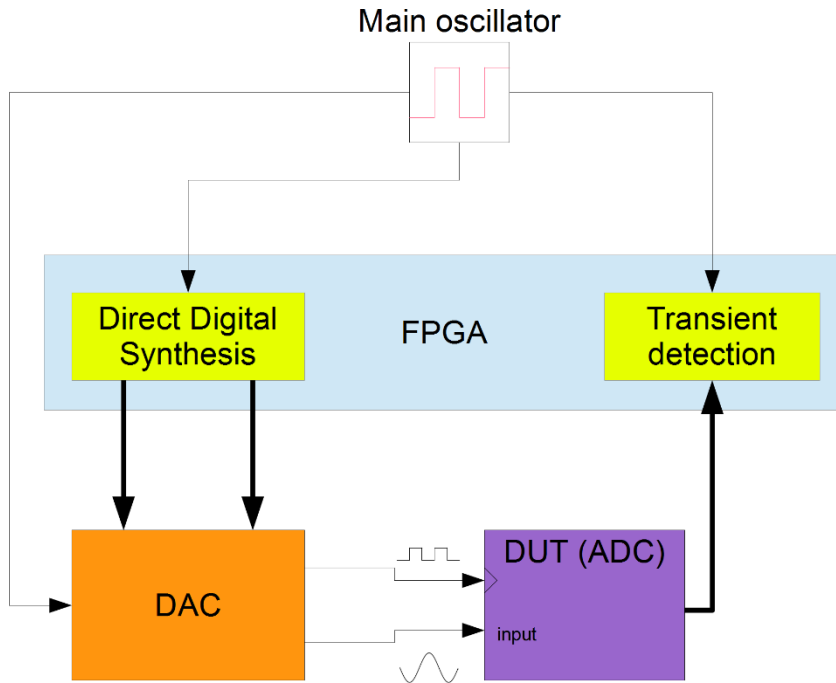
Trig condition:

$$|\text{output at } \text{clk}-m - \text{output at } \text{clk}| > \text{EB}$$

Event record:

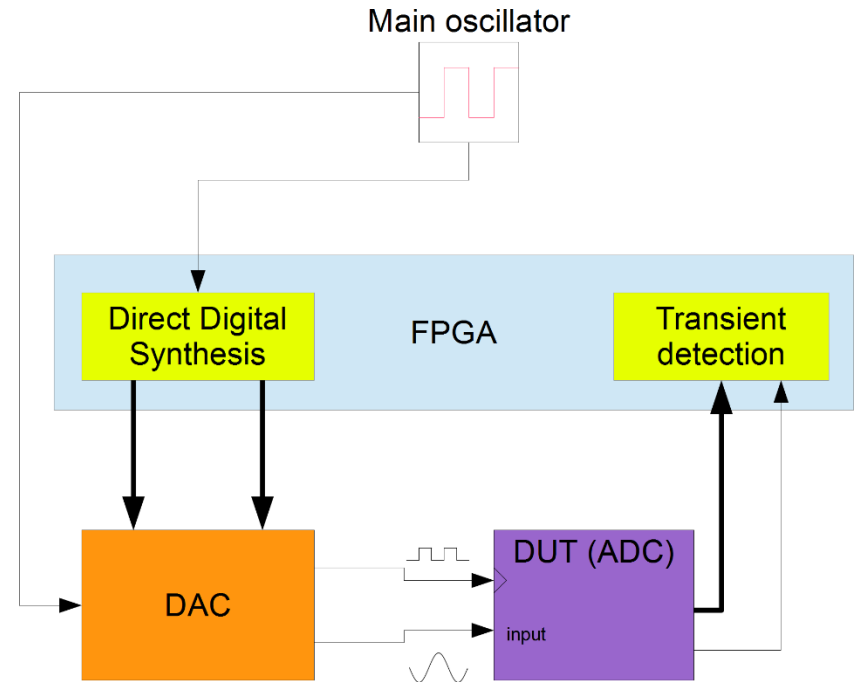
If event trig → 4096 points are recorded including pretrig points

# ADC SETUP principle



## DUT without Data ready signal

- ADS1278
- ADC128S102



## DUT with Data ready signal

- AD976A
- RHF1401

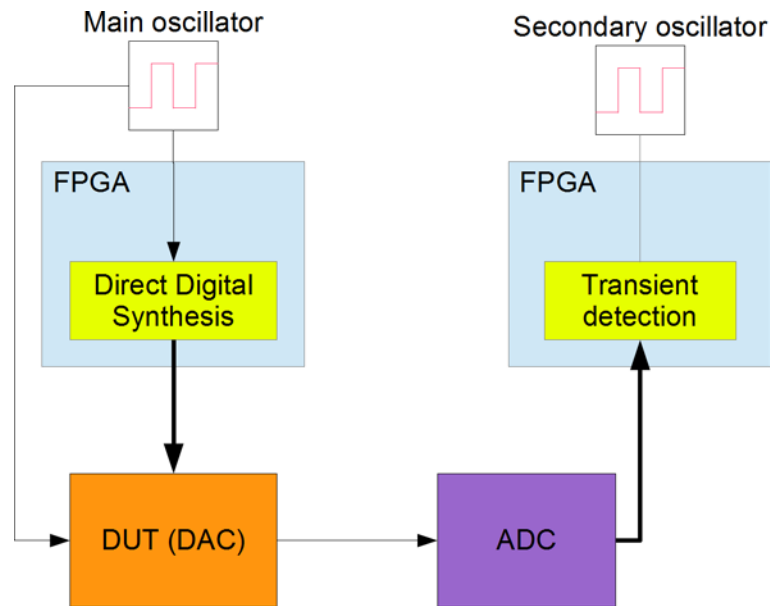
# DAC test method

DAC output is chained with a 10-bit 400 MSPS Digitizer

Trig condition: for 1MHz digital sinewave, 400 points are converted by the ADC digitizer

$$|\text{output at clock-400} - \text{output at clock}| > \text{EB}$$

Again, when 1 event is triggered, 4096 are recorded





16-Bit, 200 kSPS, BiCMOS A/D

$V_{dig}=5V$ ,  $V_{ana}=3V3$ ,  $V_{inmax}=\pm 5V$

Internal reference,  $2.2\mu F$  between REF and AGND

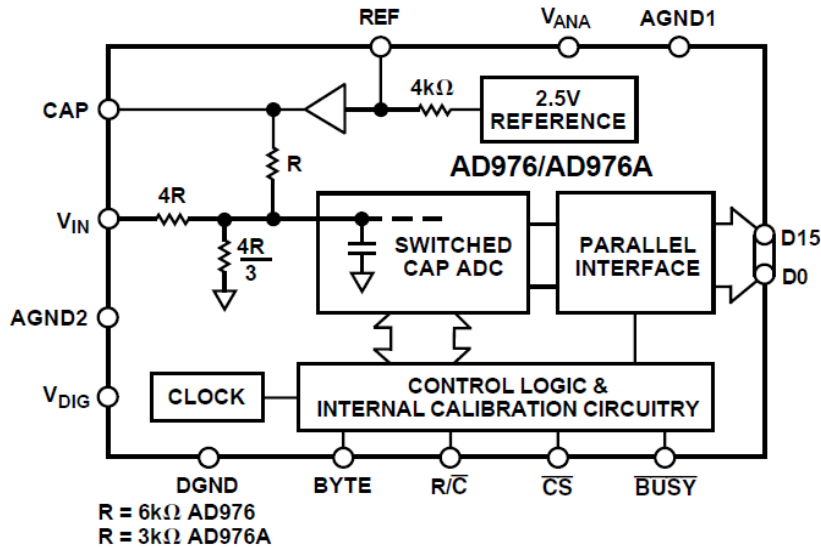
Conversion frequency=200 000 Hz

Input sine wave frequency

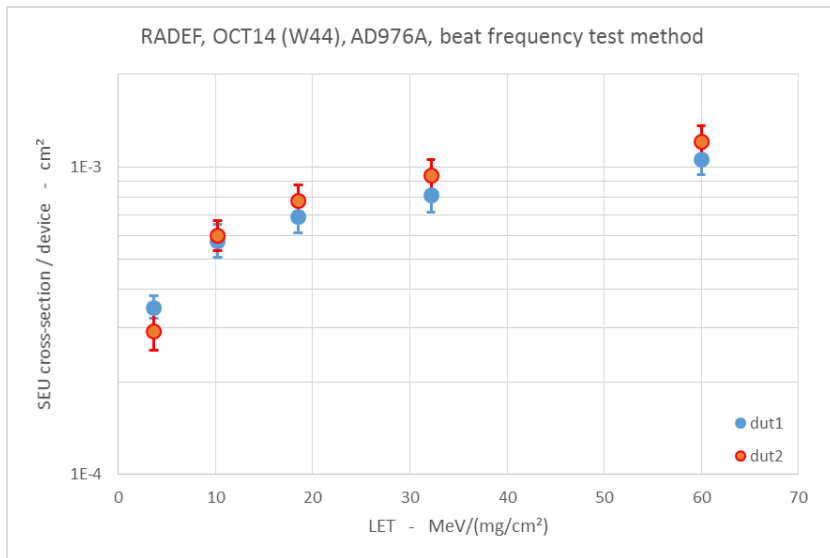
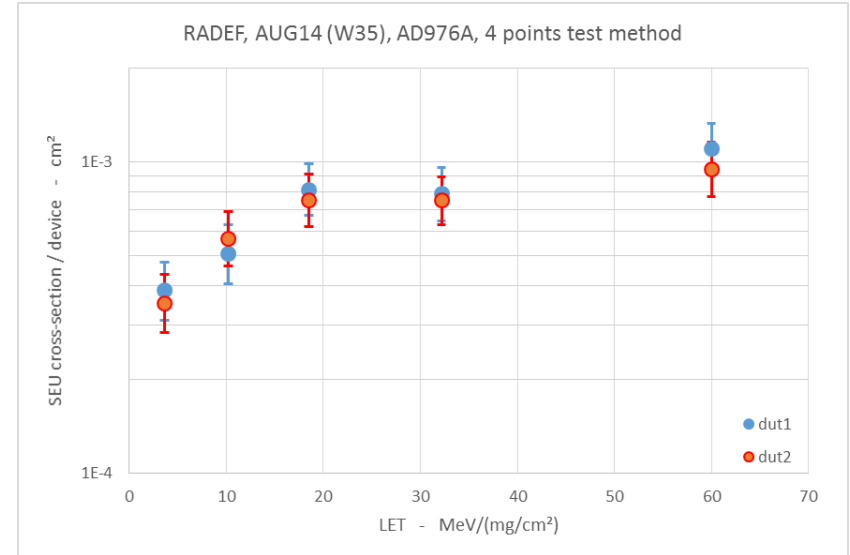
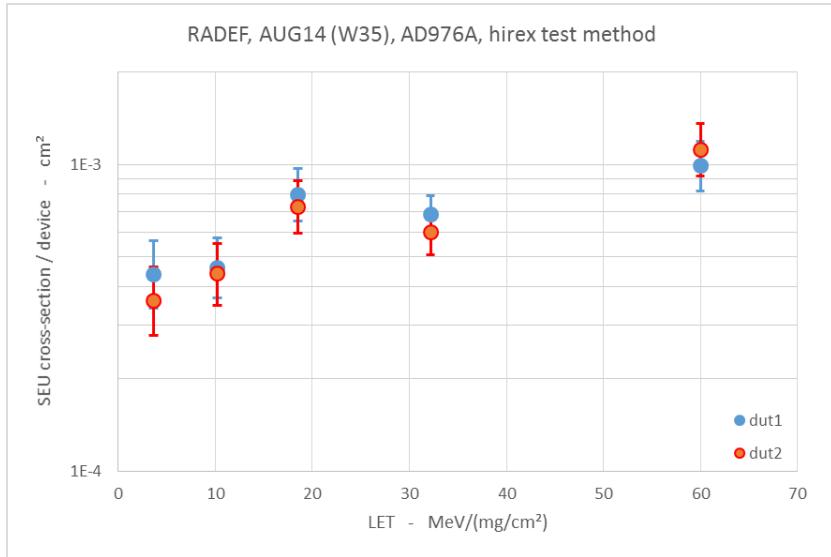
4P method      50 000 Hz

Beat frequency    199 999.03 Hz

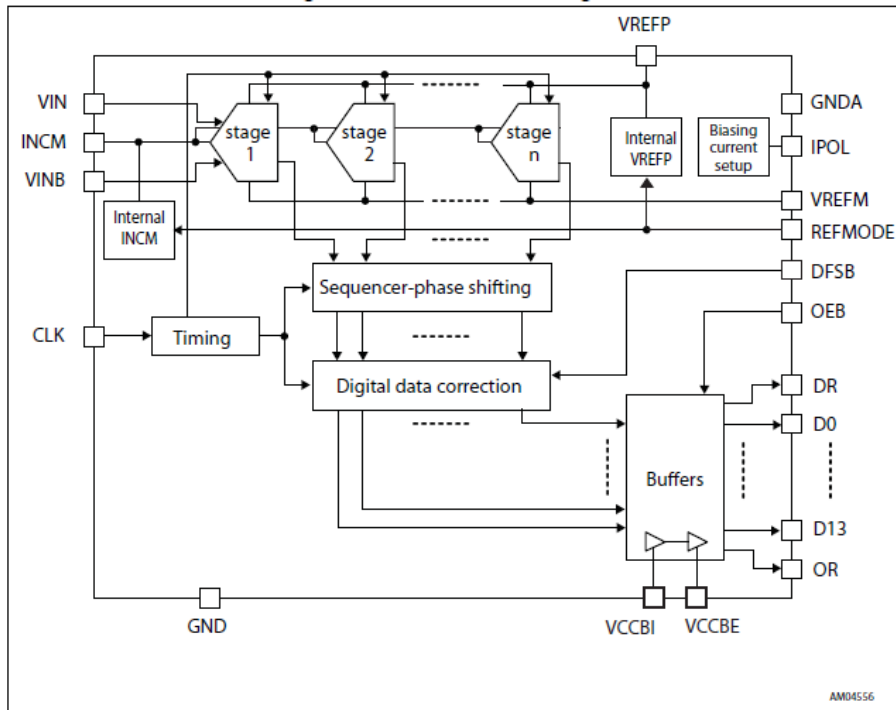
Hirex              1 560 Hz (128 points/period)



- No latchup has been detected for any run with LETs up to  $60MeV/(mg/cm^2)$
- No signal flattening nor SEFI
- Single conversion error for the 3 test methods (only 3 SETs with 2 successive conversion errors)
- Internal reference, but no large transients, can be explained by the  $2.2\mu F$  capacitor at Vref pin with the 4k Ohms internal resistor at 2.5V reference block output.
- 2 false clock pulses in total for all the runs
- The three test methods allow for similar SET events cross-section plots.



EB= 70 LSBs for the three methods



Rad-hard 14-bit 20 Msps A/D

DVCC=2.5V, AVCC=2.5V, VCCB=3.3V,  
VCCBI=2.5V

Internal reference

Conversion frequency=15 000 000 Hz

Input sine wave frequency

4P method 3 750 000 Hz

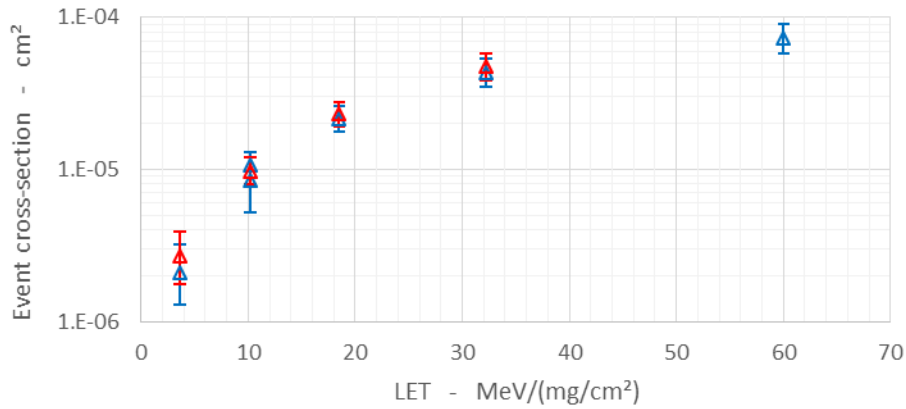
Beat frequency ~15 000 000 Hz

Hirex 15 000 Hz

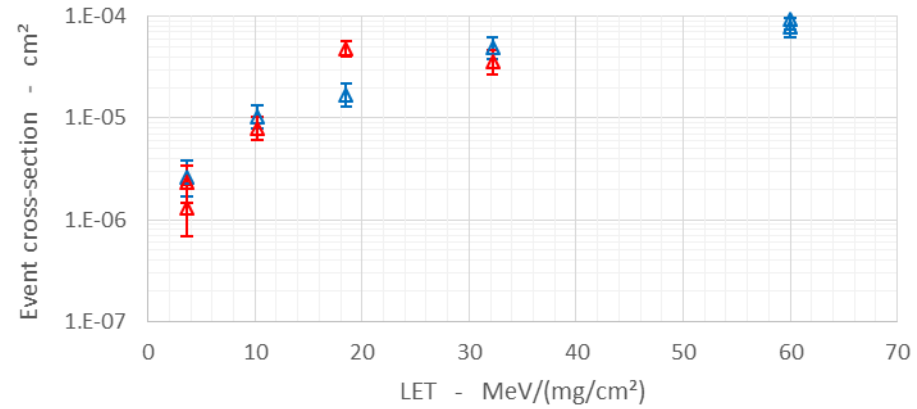
(1000 points/period)

- No latchup has been detected for any run with LETs up to 60MeV/(mg/cm<sup>2</sup>)
- No flattening nor SEFI
- Single conversion error for the 3 test methods
- Burst events that can be attributed to DUT analog block (internal reference)
- Few false clock pulses in total for all the runs
- The three test methods allow for similar SET events cross-section plots.

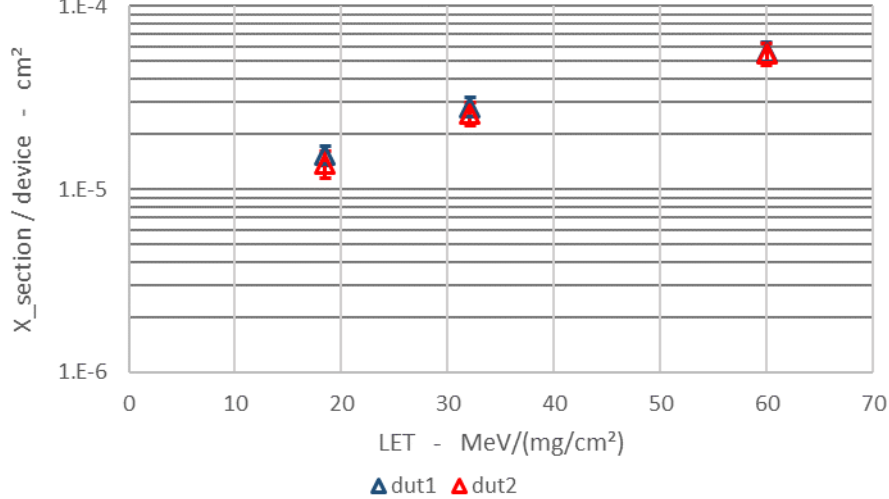
RADEF, Aug 2014, 4 points method, threshold = 100LSBs



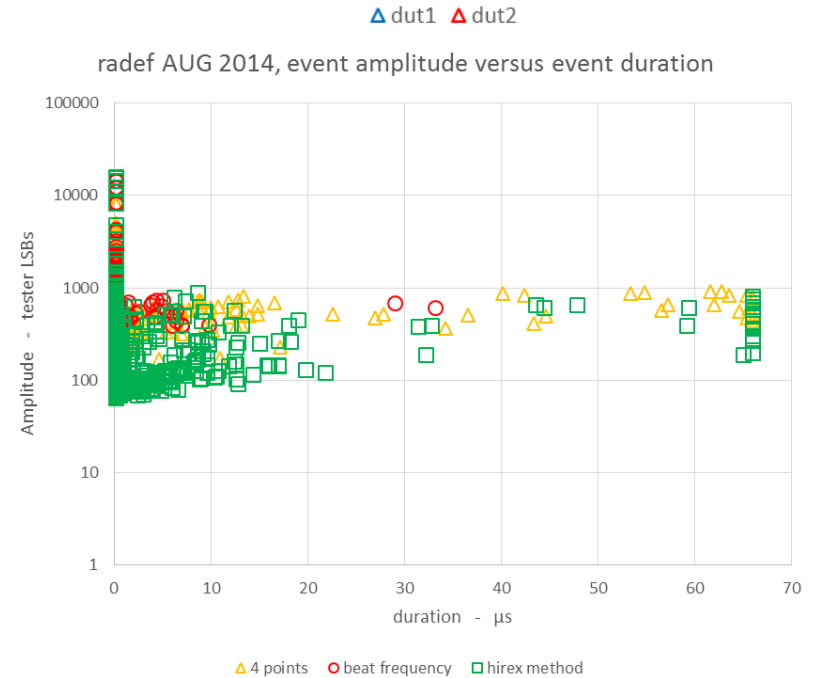
RADEF, Aug 2014, Hirex method, threshold = 100LSBs



RADEF, OCT14, beat frequency, threshold=130LSBs

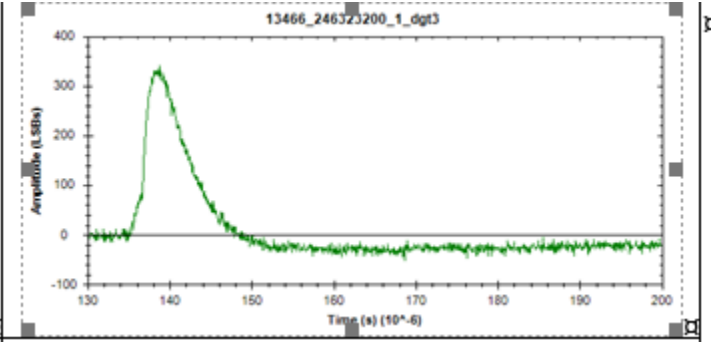
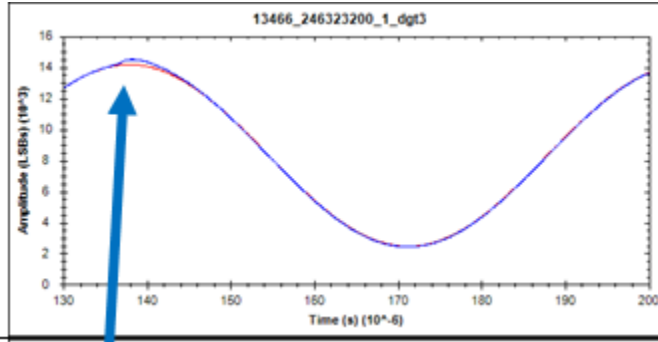


radef AUG 2014, event amplitude versus event duration

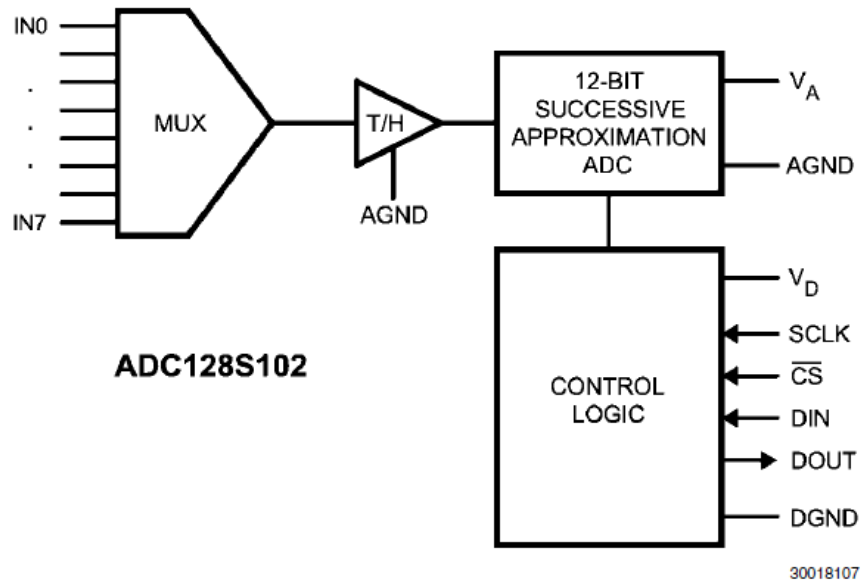


EB=100 LSBs for 4P and Hirex methods  
130 LSBs for beat frequency

#8  
RUN004-datestamp:-  
13466.246323200  
Hirex-method  
→ Xenon  
Amplitude:-390-tester-LSBs  
Duration:-32.8- $\mu$ s  
☒



# ADC128S102



8-Channel, 50 kSPS to 1 MSPS, 12-Bit A/D

$V_D=5V$ ,  $V_A=5V$ ,  $V_{INmax}= +5V$

External reference

Conversion frequency= 711 111 Hz

Input sine wave frequency

4P method 177 778 Hz

Beat frequency 711 055Hz

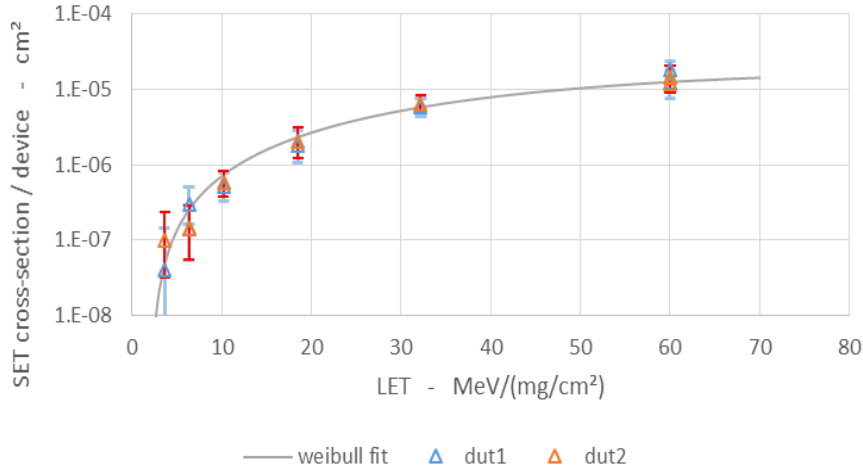
Hirex 711,1 Hz

(1000points/period)

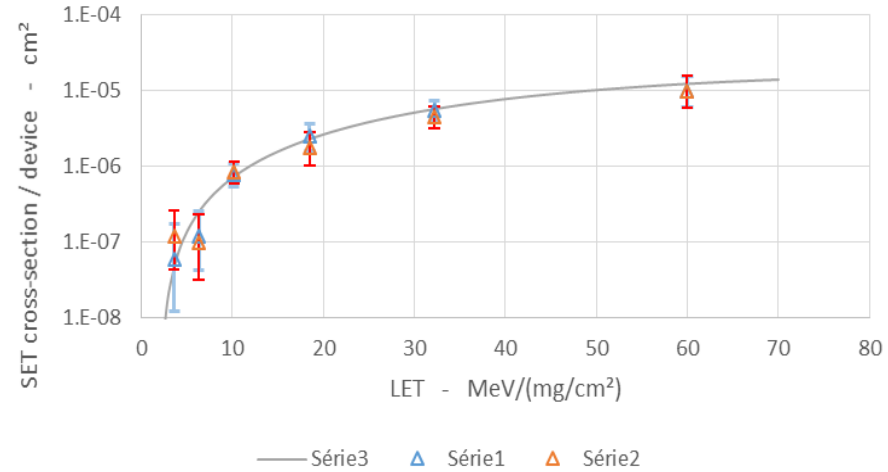
Only 1 channel is considered

- No latchup has been detected for any run with LETs up to  $60\text{MeV}/(\text{mg}/\text{cm}^2)$
- No flattening nor SEFI
- Single conversion error for the 3 test methods
- No burst event (expected as external reference)
- No clock issue as expected
- The three test methods allow for similar SET events cross-section plots.

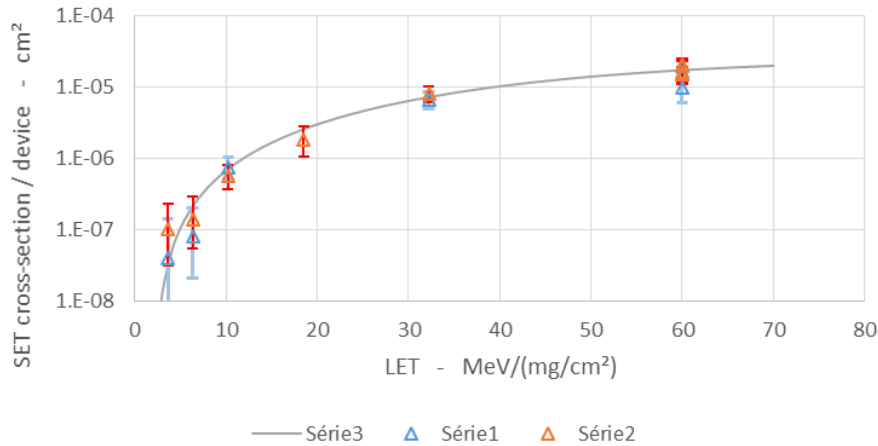
RADEF, ADC128S102, 4 points test method, threshold 4 LSBs



RADEF, ADC128S102, beat frequency test method, threshold 4 LSBs



RADEF, ADC128S102, hirex test method, threshold 4 LSBs



EB=4 LSBs for the 3 methods

# ADS1278

Octal, Simultaneous Sampling, 24-Bit A/D  
Tested as 16 bit ADC

DVDD=1.8V, AVDD=5V, IOVDD=3.3V  
VREFN= Ground, VREFP =2.048V

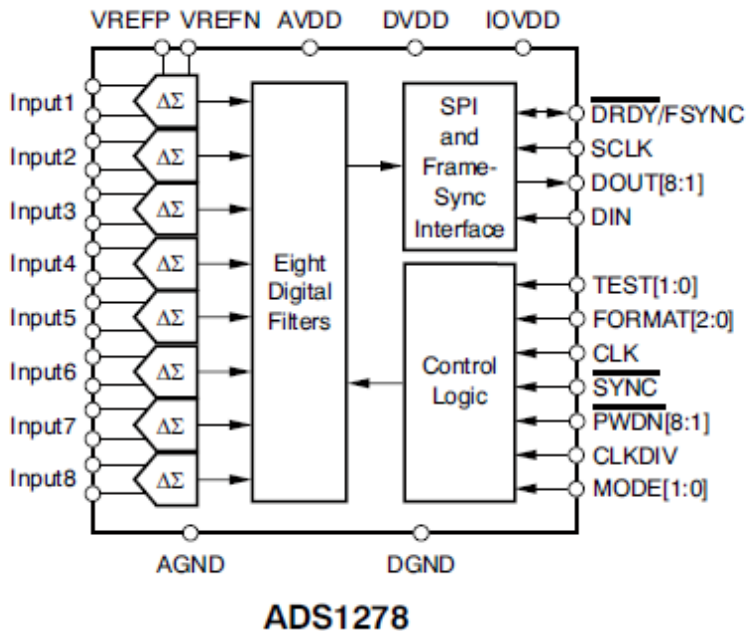
External reference

Conversion frequency= 144 000 Hz

Input sine wave frequency

|                |                       |
|----------------|-----------------------|
| 4P method      | 36 000 Hz             |
| Beat frequency | 143 998 Hz            |
| Hirex          | 720 Hz                |
|                | (200 points / period) |

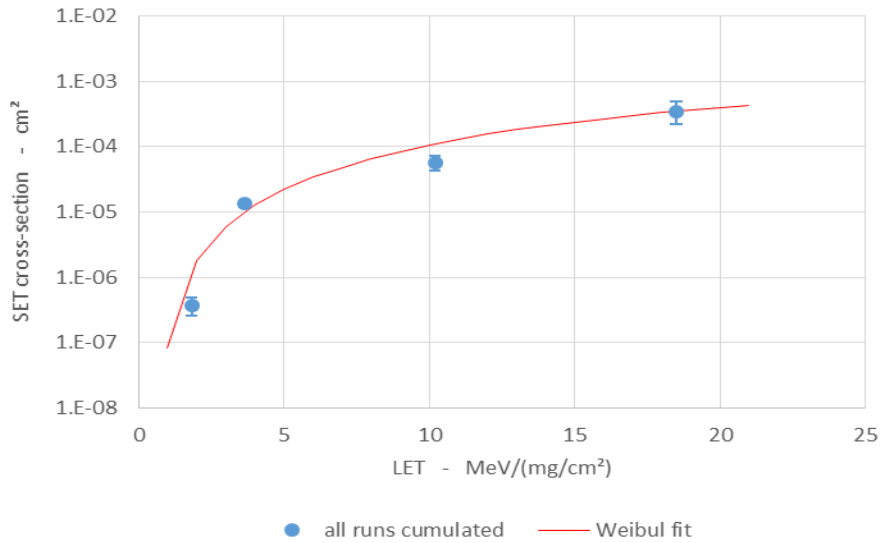
ONLY 1 A/D monitored



- SEL events have been observed with Argon (10.2 MeV/mg/cm<sup>2</sup>) and Iron (18.5 MeV/mg/cm<sup>2</sup>). Two of these SEL events were destructive.
- Flattening up to 4ms (4 events)
- Single conversion error and burst event for the 3 test methods
- No clock issue as expected
- The three test methods allow for similar SET events cross-section value for a given LET.

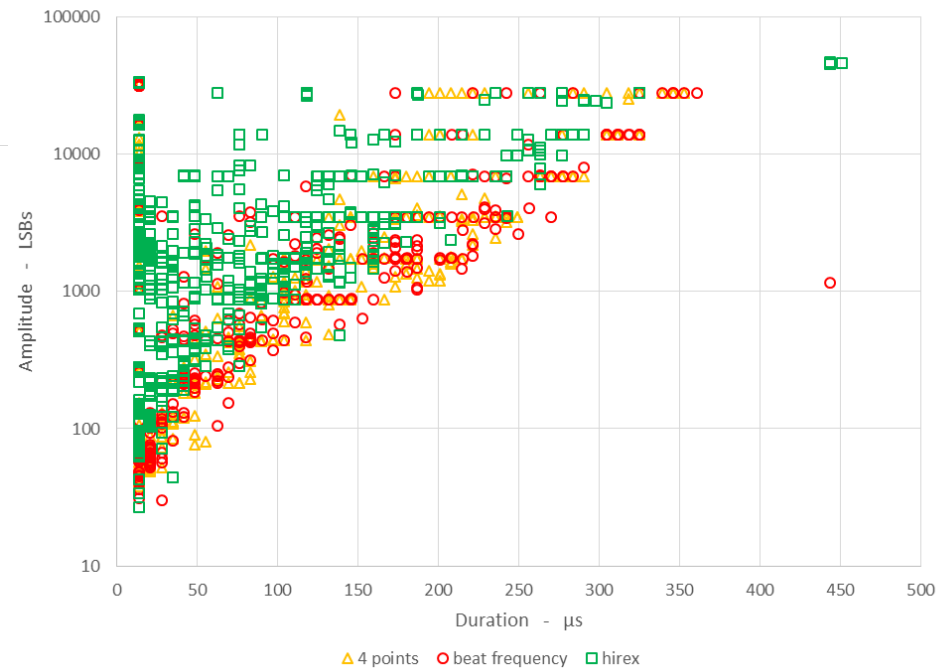


radef, October 2014, AD1278, SET cross-section (all runs cumulated)



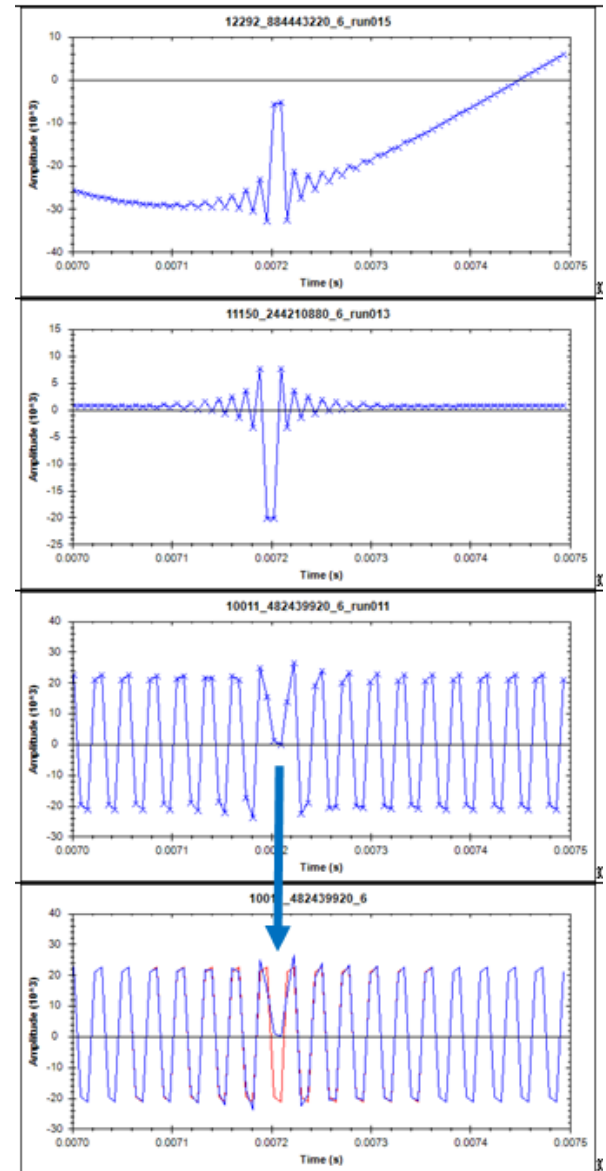
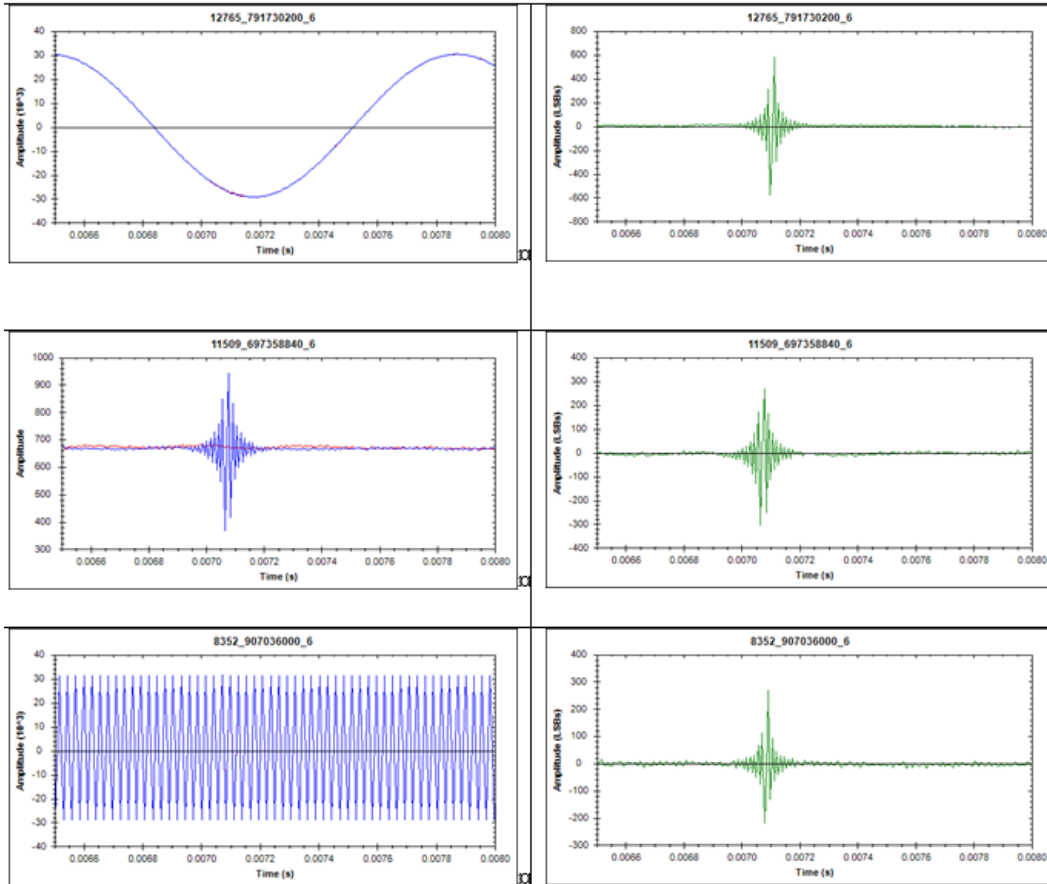
EB=70LSBs (monitored 16 bits)

radef Oct 2014, AD1278, event amplitude versus event duration



## Small bursts

## large bursts



Top: hirex  
Middle: beat frequency  
Bottom: 4P

CLASS V, 14-BIT, 400-MSPS D/A

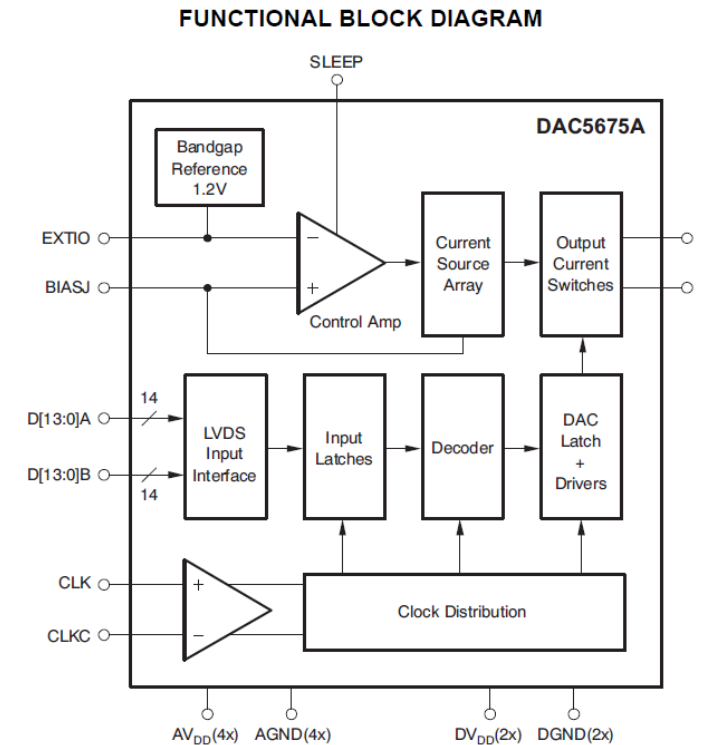
DVDD=3.3V, AVDD=3.3V

Internal reference

Clock =400 MHz

Digital Input sine wave frequency = 1MHz

Sampling digitizer frequency = 400MHz



No latchup has been detected for any run with LETs up to 60MeV/(mg/cm<sup>2</sup>)

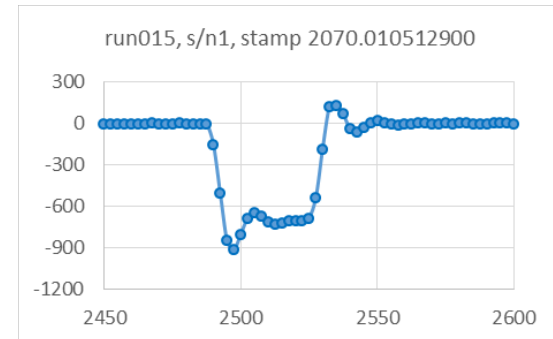
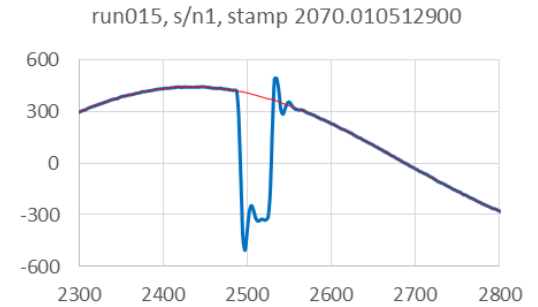
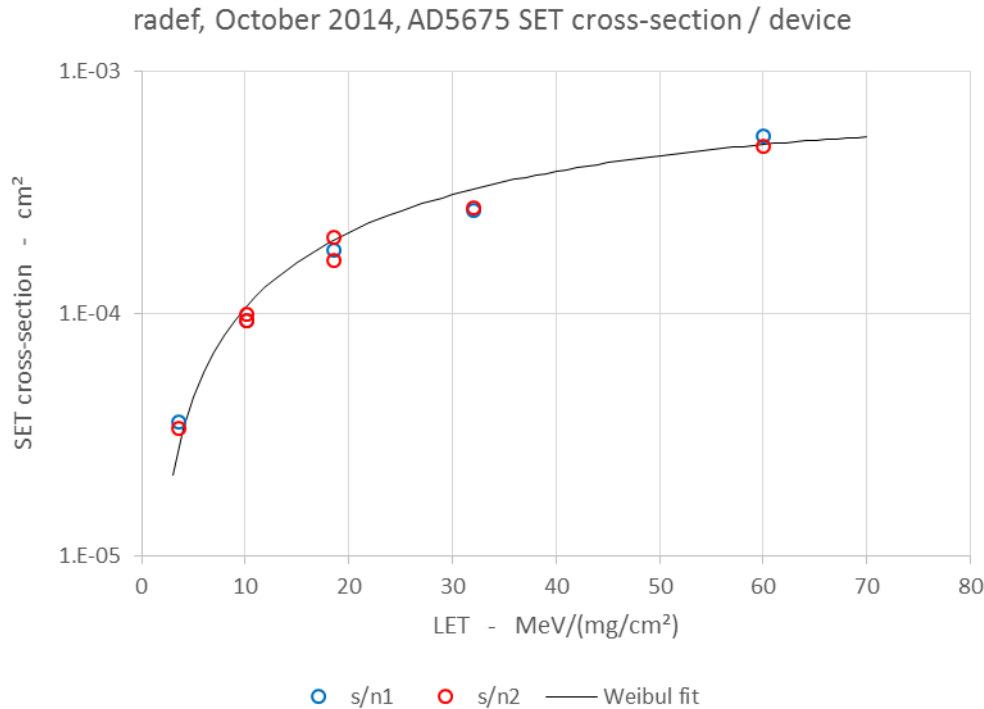
No flattening nor SEFI

All the events detected were burst events likely related to the bandgap reference burst events (expected as internal reference)

No single conversion event was detected. One hypothesis might be related to the internal current source array that should contain 2<sup>14</sup> elementary current sources and current switches. If an ion upset 1 or few current switches, the impact would be only few DUT LSBs, well inside the EB window (in tester LSBs) used.

EB= 34 LSBs (10 bit digitizer) corresponding to 612 LSBs 14 bit DUT

## Burst event example



**Amplitude=1044LSBs**  
**Duration=57.5ns**

## SET events cross-sections

- The three methods were found equivalent for providing the event cross-section curve versus LET value.

## SEE Test on DUT with Data ready signal

- RHF1401: Very few false pulses upsets have been detected with hirex method and 4 points method
- AD976A: 2 events have been detected with hirex test method.
- Beat frequency or SP methods do not allow for detecting such errors.

## Burst events

As soon as 1 conversion error trigs the recording of 4096 points (including the pretrig points), any of the three methods and even SP method were able to record burst events.

When several pretrig periods are recorded within the 4096 points, it is possible to extract the burst shape out of the perturbed output sequence.

## Flattening and / or SEFI

Such flattening events have been seen with AD1278 with hirex method and even with beat frequency. Reason is that a first error triggered the record of the 4096 points and then the short SEFI is recorded.

# Recommendations

This study has shown that having a system able to record 4096 conversion points (including pre-trig) as soon as 1 point is above the defined EB window is well adapted to the test of A/D or D/A converters.

For beat frequency and 4P methods, the testing system absolutely needs to include a module for the generation of synchronized signals (sine wave input and sampling frequency) with a very good frequency resolution for both.

For hirex method, this module is still preferable to get a more precise error detection (EB reduction), but not strictly necessary.

If a high frequency sine wave input is requested, beat frequency or 4P methods are recommended. If not hirex method is the easiest one to implement.

As already suggested in [1], and as it is easy to select and implement the different methods with the signals generation module, several methods can be used to better characterize a A/D under test (versus input frequency, smaller EB windows, etc.)

(1) : Enhancing Observability of Signal Composition and Error Signatures during SEE Analog to Digital Testing’  
– M. Berg et Al, IEEE Transactions on Nuclear Science, Volume 57, Issue: 4

# Backup Slides

# Company Overview



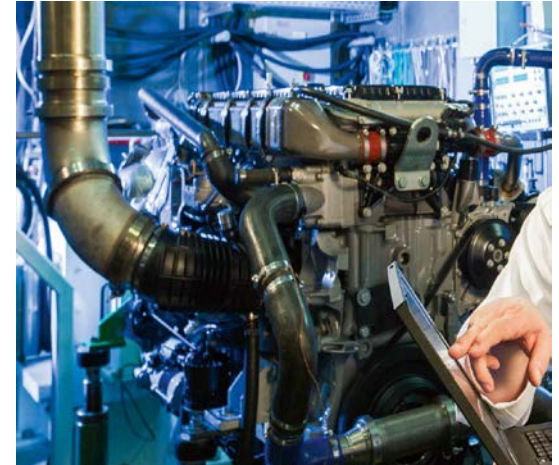
# TÜV NORD Group main areas



**ENERGY**



**IT**



**MOBILITY**



**HEALTH AND NUTRITION**

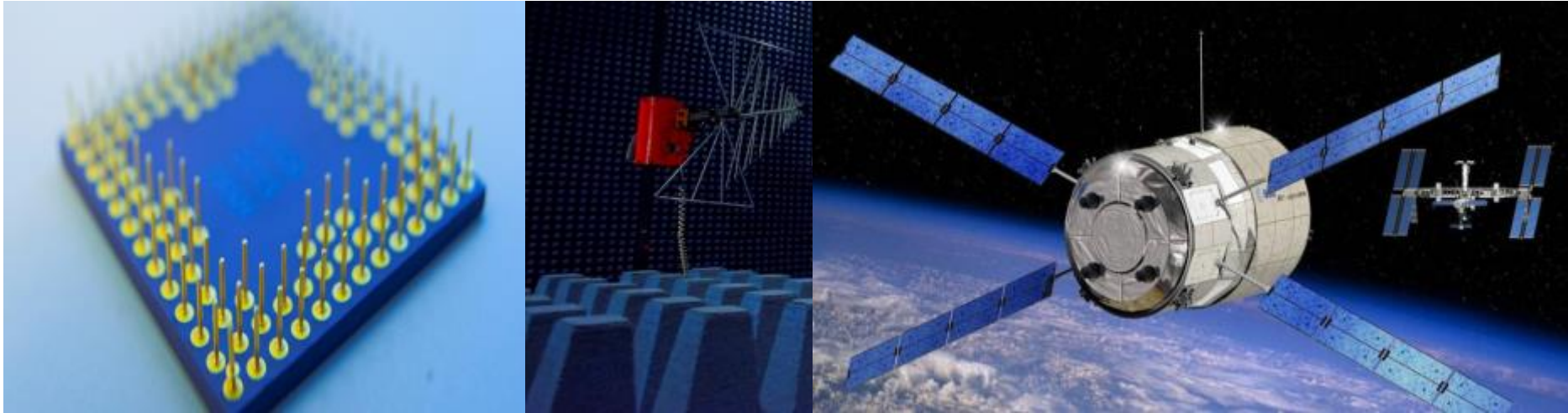


**NATURAL RESOURCES**



**AEROSPACE & ELECTRONIC**

# Aerospace & Electronic Business Unit

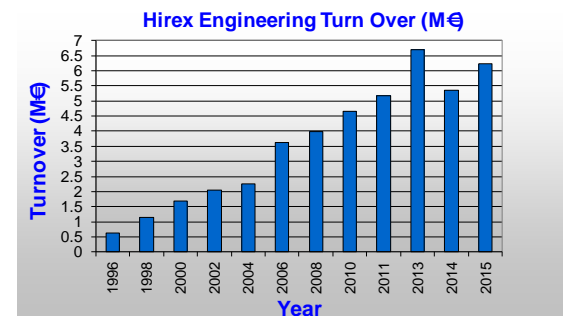
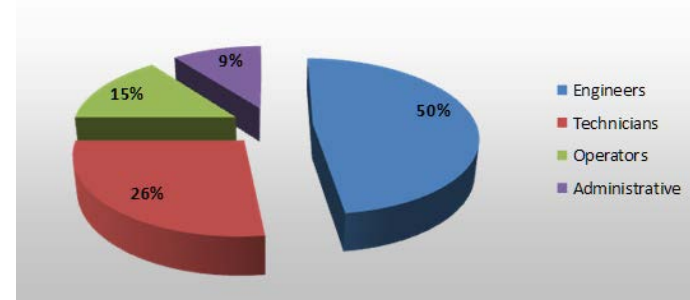


Alter technology group: with **30** years experience in the sector.



# Hirex Profile

- Hirex Engineering founded in January 1993.
- Hirex Engineering joined ALTER Technology Group in January 2007.
  - ATN based in Madrid, Seville, Roma, Portsmouth and Shanghai.
  - ATN employees 230 as of today.
  - ATN Turn-over 65 M€.
- 100% Privately owned by TÜV NORD since 29th June 2011.
- Hirex Engineering :
  - Based in Toulouse.
  - 48 employees as of today.
  - 1800 m<sup>2</sup> Facility.
  - Certified ISO 9001, EN 9100 and ISO 14001.



## 3 labs for a focused organization:

- SEE: Radiation lab.
- LAT: Semiconductor Technology lab.
- LTE: Electrical & environmental test lab

